September 2, 2026

Company name: i GRID SOLUTIONS Inc.
Name of Representative: Tomokazu Akita, President and CEO
(Securities code: 603A; Tokyo Stock Exchange Growth Market)
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Notice Regarding Drawdown of Loan under Existing Commitment Line Agreement With Financial Covenants

i GRID SOLUTIONS Inc. (the "Company") hereby announces that it has executed a loan drawdown (the "Loan Drawdown") under an existing commitment line agreement with financial covenants, as described below.

1. Purpose of the Loan Drawdown

To efficiently raise working capital.

2. Details of the Loan Drawdown

(1)	Drawdown date	August 31, 2026
(2)	Lenders	A total of 7 banks, comprising city banks and regional banks
(3)	Form of agreement	Syndicated commitment line agreement (total commitment amount: 3.0 billion yen)
(4)	Loan amount	The Company repaid 100 million yen of existing loan and borrowed an additional 2.0 billion yen.
(5)	Repayment term	From August 31, 2026 to September 30, 2026
(6)	Collateral	Unsecured

3. Financial Covenants Under the Existing Commitment Line Agreement

① The amount of net assets on the Company's non-consolidated balance sheet as of the end of each fiscal year must be maintained at no less than 75% of the greater of (i) the amount of net assets as of the end of the previous fiscal year or (ii) the amount of net assets as of the end of the fiscal year ended June 2023.

② The Company must not record an ordinary loss in its non-consolidated statement of income for any fiscal year.

4. Outlook

The impact of the Loan Drawdown on the Company's financial results for the fiscal year ending June 30, 2027 is expected to be immaterial. If any matter requiring disclosure arises, the Company will promptly disclose it.